

IN THE SPECIFICATION:

Please note that the Abstract shown below is in clean form for clarity.

In a socket to test semiconductor die, a recessed socket contact and methods of making contacts that avoid pinching the die contacts are disclosed. The socket contacts allow for smaller socket holes and allow denser contact spacing. In one embodiment, suitable for less dense contact spacing, the body of the socket contact comprises a head, a spring coupled to the head, and a shaft coupled to the spring; no outer shell is needed for the spring, as the non-conductive sides of the socket hole serve that function. In another embodiment, for use with densely spaced contacts, the body of the socket contact comprises a metal shaft having an aperture. Compression causes the shaft to buckle at the slit, thereby decreasing the amount of lateral buckling. In yet another embodiment, semiconductor fabrication techniques are used to construct a dense array of contacts.